### Extremely fine-grained Electro Magnetic Calorimeter



# fine grained calorimetry

### • why

- 1. shower shape analysis for PID
- 2. particle flow: need to track particles
- 3. separate  $\pi^0$  decay photons from direct photons
  - example at 3 m



# fine grained calorimetry

### • why

- 1. particle flow: need to track particles
- 2. shower shape analysis
- 3. separate  $\pi_0$  decay photons from direct photons
- what
  - lateral 1 mm, longitudinal 1  $X_0$
  - small Moliere radius  $\rightarrow$  compact, W + silicon
- many channels
  - only feasible with digital calorimetry, i.e. particle counting
    - particle density 10<sup>3</sup> mm<sup>-2</sup>
    - may need even more, smaller pixels!

### 100 GeV $\pi^0$ GEANT simulation 0.1 mm pixels, 24 layers 1.14 $X_0$





















2

1.5

0.5

0

-0.5

-1

-1.5

-2∟ -2

Y (cm)



RD11























X (cm)





RD11































Y (cm)





X (cm)

GJN24

RD11























- $\ensuremath{\textcircled{\odot}}$  solves the connection problem between sensor and front-end
- Short input connections -> extremely low noise: tens of electrons
  1 MIP = 80 e/h-pairs per micron
- ⊗ high power density in sensor: dark current, cooling
- ☺ relatively slow -> not selftriggering
- ⊗ charge collection
- ⊗ radiation tolerance
- ⊖ thin active layer
- ③ intense development at several places, like RAL, IPHC, CERN

# an implementation in 0.35 AMS: MIMOSA26





### 21.5 mm

- "rolling shutter" readout
  - 115 µs per frame
  - 115 µs charge integration
- row-wise discrimination
- built-in zero suppression



# sketch of a tungsten + MAPS calorimeter

- digital areas of chips are dead -> need overlap
- each layer is composed of two rotated halflayers
- W is good heat conductor
  - glue chips directly on it
  - cool from the sides: 1 K/W



## a design for one halflayer

### Al+kapton flex can be bonded directly on chip



### MAPS data volume

- 1. total silicon area 24 layers of 1 m<sup>2</sup>  $\sim$  24 m<sup>2</sup>  $\rightarrow$  10<sup>10</sup> pixels  $\rightarrow$  10 Gbit eventsize
- 2. rolling shutter provides full frame every 20  $\mu$ s  $\rightarrow$  0.5 PB/s
- technical feasibility
  - 2 kHz full read-out, see next slide



### MAPS data volume, an estimate

- 1. total silicon area 24 layers of 1 m<sup>2</sup>  $\sim$  24 m<sup>2</sup>  $\rightarrow$  10<sup>10</sup> pixels  $\rightarrow$  10 Gbit eventsize
- 2. rolling shutter provides full frame every 20  $\mu$ s  $\rightarrow$  0.5 PB/s
- 3. data reduction
  - a. select/compress locally, in layer or chips
    - zero suppress depends on occupancy, high for chips at core of the shower
  - *b.* selection at end of tower (16 chips per layer)
    - transport only frames with trigger
  - c. outside

high speed cabling, fibers combine frames

locally, bandwidth need remains high because of high particle density in shower

> different from tracker application

suppose we can measure this, what can we do with it?





## geometrical resolution





easy to find peakposition to submillimetre, what about energy?

### energy measurement "vide-pomme"





- cut out cylinder along shower axis
- count hit pixels for *energy measurement*

simulations for single photons with different cylinder radii





### energy resolution



### Fine grained EM Calorimeter

## "real" prototype

- uncertainties in simulation
  - small angles
  - low energy particles
  - thin sensor, charge collection (not simulated here)
- build prototype and test with beam
  - need sensor size compatible with  $R_{\rm M}$
  - enough layers to study longitudinal shower development
  - based on available MAPS sensors
    - most are too small, like TPAC, many MIMOSA
    - all have pixel < 50  $\mu$ m
    - ➤ take PHASE1 from IPHC

# Beam test prototype objectives

### • YES:

- proof-of-principle
  - resolution
  - Moliere radius
- technology demonstrator
  - manage read-out at GB/s
  - cooling
  - integration
  - overlap, needed because of dead zones
- collect data for study of
  - data volume/flow, data reduction
  - pixel size
- NO:
  - final chip (too slow)
  - rad hard
- may help in
  - detector simulation

# prototype features

- 24 layers 3 to 4 mm W
- PHASE1/MIMOSA23
  - 640 \* 640 pixels, 30 µm pitch
  - high resistivity (400  $\Omega cm$  ) epilayer, 15 and 20  $\mu m$
  - 1 MHz rolling shutter  $\rightarrow$  640 µs integration time
  - 160 MHz read-out clock
  - no data reduction on board
  - radiation tolerance < 1 Mrad</li>
- thinned to 120 µm
  - total sensor layer thickness ~1 mm
  - estimated  $R_{\rm M}$  < 15 mm
- 4 PHASE1 per layer:
  - 4 \* 4 cm<sup>2</sup> active area
  - overlap dead areas
- full read-out



### some details



Tungsten (1500um thick)

idea of direct gluing to W discarded:

- what to do with broken chips?
- need thin flex development
- use intermediate carrier (pcb) instead

keep small overlap 100 µm



## beam test prototype

- 4 PHASE1 per layer: 24 \* 4 cables from tower to read-out
- total 61 Gb/s
- several FPGA's to manage this: keep only 2 frames per trigger big local buffer storage small duty factor of PS/SPS



electron beam

- CERN PS Nov 2011
- CERN SPS 2012



### read-out electronics (one half)



Fine grained EM Calorimeter

## summary, outlook



EM calorimeter with fine sampling and pixel counting is within reach

> would open new possibilities for particle identification

- uncertainties in simulations
  - shower development on this scale
  - importance of low-energy particles
  - charge collection
- prototype under construction (Utrecht/Nikhef, Bergen)
  - extremely fine pitch
  - full data read-out
  - very small Moliere radius
- an option for future forward calorimeter in ALICE



# digital calorimetry



Richard Wigmans at EDIT2011 "was tried and abandoned in 1983, for good reasons: particle density in the core of EM showers is very high"

non-linearity





Paul Dauncey at ICHEP 2010 "improved resolution"

– beware: GEANT not tested at  ${\sim}50~\mu m$  scale

simulation for CALICE ECAL



### issues



- pixel size:
  - current designs  $\approx$  20  $\mu$ m
  - 50 .. 100 µm sufficient?
    - charge collection?
- trigger:
  - too slow for self triggering
  - need separate fast detector
    - S fast Si or scintillator at around shower maximum

- power consumption:
  - currently  $\approx 100 \text{ mW/cm}^2 \text{ sensor}$ 
    - more functions  $\uparrow$
    - newer technology  $\checkmark$
- integration time:
  - pixel charge is integrated until next read-out
  - maximise rollingshutter speed
    - technology limit ~0.2  $\mu s/row$
    - shorter columns



shapes for  $\gamma$  and  $\pi$  with equal deposited energy (~10 GeV  $\gamma$ )

## MAPS half layer





### multilayer PCB

- is substrate for PHASE1
- connects bondwires to macroscopic world
- components for power regulation and filtering
- clock and signal at 160 MHz
- has connector for chiptesting, to be replaced by flatcable for read-out